S1C17554/564



16-bit Single Chip Microcontroller

- ■48-pin wafer-chip-scale package (WCSP)
- ●10-bit A/D converter
- Code-efficient architecture optimized for the C language, single-cycle instruction high processing performance, serial ICE, and built-in 16-bit RISC PCU core S1C17

■ DESCRIPTIONS

The S1C17554/564 is a compact 16-bit MCU that delivers high-speed, low power operation with large address space and on-chip ICE. It integrates A/D converter and thus various analog-interface sensors are connectable. The ultra small power-saving 48-pin WCSP is most suitable for sensor-applied products that require low power consumption and high-speed processing.

■ FEATURES

The main features of the S1C17554/564 are listed below.

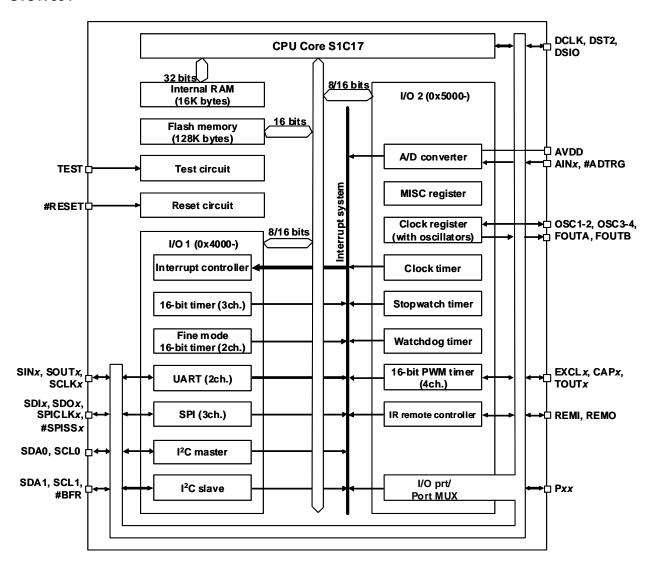
Model	S1C17554	S1C17564	
CPU			
CPU core	Seiko Epson original 16-bit RISC CPU core S1C17		
Multiplier/Divider (COPRO)	16-bit × 16-bit multiplier 16-bit × 16-bit + 32-bit multiply and accumulation unit 16-bit ÷ 16-bit divider		
Embedded Flash memory			
Capacity	128K bytes (for both instructions and data)		
Erase/program count	Min. 1 time		
Other	 Read/program protection function An erasing/programming power supply (VPP) is required. Allows on-board programming using a debugging tool such as ICDmini. 		
Embedded RAM	, ,		
Capacity	16K bytes		
Clock generator			
System clock source	2 sources (OSC3/OSC1)	3 sources (IOSC/OSC3/OSC1)	
IOSC oscillator circuit		2/4/8/12 MHz(typ.) internal oscillator circuit	
OSC3 oscillator circuit	Supports an external clock input.	24 MHz (max.) crystal or ceramic oscillator circuit Supports an external clock input.	
OSC1 oscillator circuit	32.768 kHz (typ.) crystal oscillator ci Supports an external clock input.	32.768 kHz (tvp.) crystal oscillator circuit	
Other	Core clock frequency control Peripheral module clock supply control		
I/O ports			
Number of general-purpose I/o ports	Max. 40 bits (TQFP13-64pin package) Max. 34 bits (WCSP-48 package) (Pins are shared with the peripheral I/O.)	Max. 40 bits (Pins are shared with the peripheral I/O.)	
Serial interfaces			
SPI	3 channels	3 channels	
I ² C master (I2CM)	1 channel	1 channel	
I ² C slave (I2CS)	1 channel		
UART	2 channels (IrDA1.0 supported)	2 channels (IrDA1.0 supported)	
IR remote controller (REMC)	1 channel		
Universal serial interface (USI)		2 channels (Usable as a UART, SPI, or I ² C)	
Timers			
16-bit timer (T16)	3 channels		
Fine mode 16-bit timer (T16F)	2 channels		
16-bit PWM timer (T16A)	4 channels		
Clock timer (CT)	1 channel		
Stopwatch timer (SWT)	1 channel		

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Watchdog timer (WDT)	1 channel		
A/D converter	1		
Conversion method	Successive approximation type		
Number of analog input channels	4 channels (max.)		
Resolution	10 bits		
Interrupts			
Reset interrupt	#RESET pin		
NMI	Watchdog timer		
Programmable interrupts	23 systems (8 levels)		
Power supply voltage			
Core voltage (LVDD)	1.65 V to 1.95 V	1.65 V to 1.95 V (Not required when the	
1/0 1/2 (11) (DD)	4.05.7/4- 5.5.7/	regulator is used.)	
I/O voltage (HVDD)	1.65 V to 5.5 V	2.0 V to 5.5 V (Regulator used) 1.65 V to 5.5 V (Regulator not used)	
Analog voltage (AVDD)	2.7 V to 5.5 V		
Flash programming voltage (VPP)	7 V/7.5V		
Regulator			
Input voltage		2.0 V to 5.5 V	
Output voltage		1.8 V	
Other		Enables the system to operate with a 3.3 V or	
		5.0 V single power supply.	
Operating temperature		gio i diligio porrei dappi.	
Operating temperature range	-40° C to 85° C		
Current consumption (Typ value, LVDD = HVDD = 1.8 V)			
SLEEP state	0.8 µA	1.2 μΑ	
	(OSC1 = Off, OSC3 = Off)	(OSC1 = Off, IOSC = Off, OSC3 = Off)	
HALT state	2.7 µA (OSC1 = 32 kHz, OSC3 = Off)	3.1 μA (OSC1 = 32 kHz, IOSC = Off, OSC3 = Off)	
Run state	16 μA (OSC1 = 32 kHz, OSC3 = Off)	16 μA (OSC1 = 32 kHz, IOSC = Off, OSC3 = Off)	
	3000 μA (OSC1 = Off, OSC3 = 8 MHz ceramic)	3000 µA (OSC1 = Off, IOSC = Off, OSC3 = 8 MHz ceramic)	
		4500 μA (OSC1 = Off, IOSC = 12 MHz, OSC3 = Off)	
A/D conversion	380 μA (AVDD = 3.6 V, 100 kHz sampling, FSEL[1:0] = 0x0, XPD[1:0] = 0x3)		
Shipping form			
1	TQFP13-64pin (10 mm × 10 mm × 1.0 mm, lead pitch: 0.5 mm)		
2	Die form (3.137 mm × 3.137 mm, pad pitch: 140 μm)		
3	WCSP-48 (3.137 mm × 3.137 mm × 0.72 mm,		
	ball pitch: 0.4 mm)		

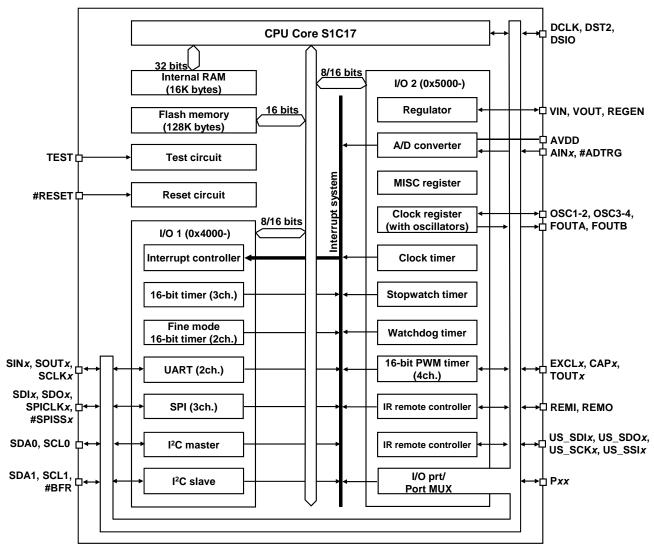
■ BLOCK DIAGRAM

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